

AF/6A 1765  
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Correspondence and Mail  
BOX AF



Response Under 37 C.F.R. 1.116  
Expediting Procedure  
Examining Group 1765

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: HENNHÖFER ET AL.

SERIAL NO.: 09/032,305

EXAMINER: R. KUNEMUND

FILED: FEBRUARY 27, 1998

GROUP: 1765

TITLE: PROCESS FOR TREATING A POLISHED SEMICONDUCTOR WAFER  
IMMEDIATELY AFTER THE SEMICONDUCTOR WAFER HAS BEEN  
POLISHED

TO 1100 MAIL ROOM

SEP 15 2000

RECEIVED

direct enter  
over  
9/2/00

Entered - CPA  
10/6/00

AMENDMENT IN RESPONSE TO FINAL OFFICE ACTION

ATT: BOX AF  
Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

In response to the Final Office Action dated JUNE 12, 2000  
please amend the above-identified patent application as follows:

IN THE CLAIMS:

Please cancel claim 1 without prejudice and please replace by  
inserting new claims 14 as follows:

- Sub D1  
C
14. Process for treating a semiconductor wafer, comprising  
polishing the semiconductor wafer;  
immediately after polishing the semiconductor wafer  
removing the semiconductor wafer from a polishing plate;  
bringing the semiconductor wafer into contact with an